



ISO9001 & ISO14001 & TS16949 **CHILISIN ELECTRONICS CORP.**

Lead-Free & RoHs Compliance!!

SPECIFICATION FOR APPROVAL

CUSTOMER : EL TECH

CUSTOMER P/N : _____

OUR DWG No : CE1-370004

QUANTITY : X **Pcs.** **DATE :** 2013/7/3

ITEM : LVM202012-2R2M-NT

| SPECIFICATION | |
|----------------------------|--|
| ACCEPTED BY: | |
| COMPONENT ENGINEER | |
| ELECTRICAL ENGINEER | |
| MECHANICAL ENGINEER | |
| APPROVED | |
| REJECTED | |

| | |
|---|---|
| <p>奇力新電子股份有限公司 CHILISIN ELECTRONICS CORP. NO.29,LANE 301,TEHHSIN ROAD,HUKOU, HSINCHU,TAIWAN,303, REPUBLIC OF CHINA TEL : (03) 599-2646 FAX : (03) 599-9176 E-mail : Sales@chilisin.com.tw http : //www.chilisin.com.tw</p> <p>台北營業處 TAIPEI OFFICE 3F,NO.233-1,PAO-CHIAO ROAD, HSIN TIEN,TAIPEI,TAIWAN, R.O.C. TEL : (02)29112073 FAX : (02)29147698 E-mail : Sales@chilisin.com.tw</p> | <p>東莞奇力新電子有限公司 DONG GUANG CHILISIN ELECTRONICS LTD. YULIANGWEI ADMINISTRATION AREA, QINGXI TOWN, DONGGUANG, GUANGDONG, CHINA TEL : 00286769-7730251~3 FAX : 00286769-7730232 E-mail : cect@chilisin.com.tw</p> <p>奇力新電子(蘇州)有限公司 CHILISIN ELECTRONICS(SUZHOU)CO.,LTD NO.10, Zhu Yuan Road, Suzhou New District, Suzhou,P.R.C. TEL : 00286512-8255568 FAX : 00286512-8255568 E-mail : suzhou@chilisin.com.tw</p> |
|---|---|

| | | |
|--|---|--|
| DRAWN BY 陳秋霞 candy.chen | CHECKED BY 鍾德慶 shawn.zhong | APPROVED BY 陳瑞揚 ryan.chen |
|--|---|--|

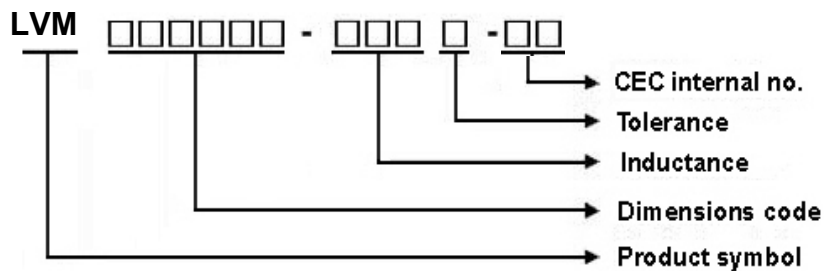
YG12B01561



LVM202012 Series Specification

1 Scope: This specification applies to SMD Power Inductor

2 Part Numbering: Product Identification



3 Rating:

Operating Temperature range: $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$ (Including self - heating)

Storage Temperature range: $-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$ (For products in unopened tape package -5 to 40°C)

4 Marking:

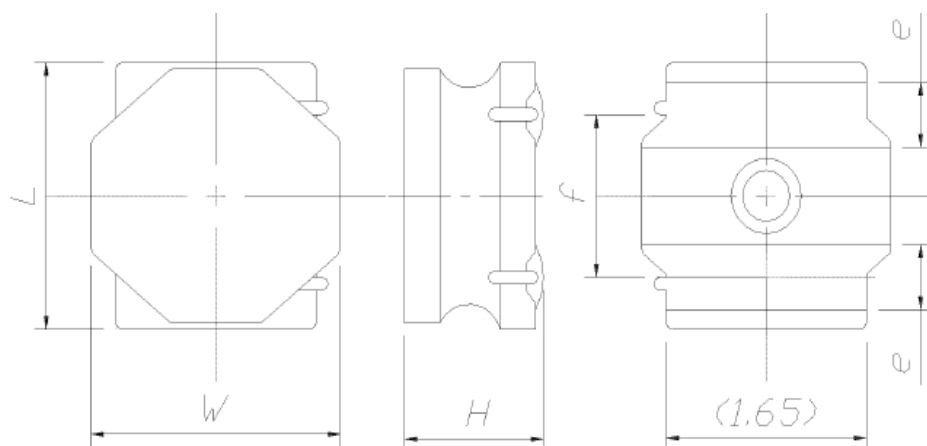
NO Marking

5 Standard Testing Condition

| | Unless otherwise specified | In case of doubt |
|-------------|---|----------------------------|
| Temperature | Ordinary Temperature($20 \pm 15^{\circ}\text{C}$) | $20 \pm 2^{\circ}\text{C}$ |
| Humidity | Ordinary Humidity($65 \pm 20\%$) | $65 \pm 5\%$ |

LVM202012 Series Specification

6 Configuration and Dimensions:



| Description | Mark | Dimensions |
|--------------------------|------|----------------|
| Length | L | 2.0 ± 0.15 |
| Width | W | 2.0 ± 0.15 |
| Height | H | 1.2Max. |
| Width of Electrode | e | 0.50 ± 0.2 |
| Space between electrodes | f | 1.25 ± 0.2 |

(Unit: mm)

7 ELECTRICAL CHARACTERISTICS :

| Ordering Code | Nominal Inductance [μH] | Inductance Tolerance [%] | D.C. Resistance [mΩ] | | Rated Current [mA] | | | |
|-------------------|----------------------------|-----------------------------|-------------------------|-----|---------------------------------|---------------------------------------|---------------------------------|---------------------------------------|
| | | | Typ | Max | Saturation Current Idc1(Typ) | Temperature Rise Current Idc2(Typ) | Saturation Current Idc1(max) | Temperature Rise Current Idc2(max) |
| LVM202012-2R2M-NT | 2.2 | ±20 | 95 | 109 | 2000 | 1550 | 1750 | 1450 |

Absolute maximum voltage: DC25V

- *) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20 deg C)
- *) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40 deg C. (at 20 deg C)
- *) The rated current is the DC current value that satisfies both of current saturation current value and temperature rise current value.



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※ Caution for Temperature Rise.

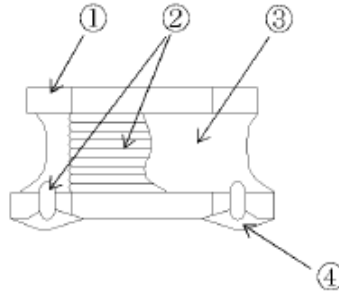
Temperature rise of this inductor depends on the installed board condition.

It shall be confirmed in the actual end product that temperature rise of inductor is within operating temperature.

LVM202012 Series Specification

8 LVM202012 Series

structural drawing

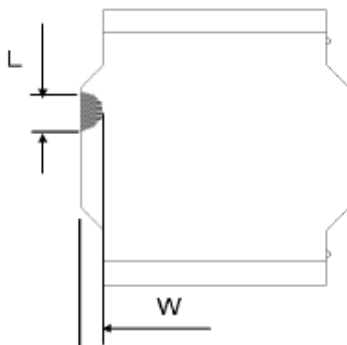


- | | | |
|----------------------|---|----------|
| ① Core | Metal magnetic core | |
| ② Winding wire | Polyurethane-copper wire | |
| ③ Over-coating resin | Epoxy resin, containing Metal magnetic powder | |
| ④ Electrode | External electrode (substrate) | Ag |
| | External electrode (top surface solder coating) | Sn—Ag—Cu |

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Core chipping

The appearance standard of the chipping size in top side, of bottom side metal magnetic core is following dimension.



| L | W |
|-----------|-----------|
| 0.4mmMax. | 0.4mmMax. |



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10 TEST DATA FOR PREPRODUCTION SAMPLES

QF-1419

DESCRIPTION: LVM202012-2R2M-NT

| MEAS. Item | L (uH) | RDC (mΩ)Max | Isat (mA)Typ. | | L m/m | W m/m | H m/m | | | | |
|---------------|-----------|----------------|------------------|------|----------|----------|----------|--|--|--|--|
| Spec | Customer | 2.2±20% | | | | | | | | | |
| | Suggest | | 109 | 2000 | 2.0±0.15 | 2.0±0.15 | 1.2 Max. | | | | |
| Test Freq. | 1MHz 1V | | | | | | | | | | |
| 1 | 1.96 | 106 | 2000 | | 2.06 | 2.04 | 1.15 | | | | |
| 2 | 1.94 | 104 | 2100 | | 2.06 | 2.04 | 1.16 | | | | |
| 3 | 2.00 | 105 | 2000 | | 2.07 | 2.05 | 1.14 | | | | |
| 4 | 1.92 | 108 | 2100 | | 2.06 | 2.05 | 1.14 | | | | |
| 5 | 1.94 | 106 | 2100 | | 2.07 | 2.06 | 1.13 | | | | |
| 6 | | | | | | | | | | | |
| 7 | | | | | | | | | | | |
| 8 | | | | | | | | | | | |
| 9 | | | | | | | | | | | |
| 10 | | | | | | | | | | | |
| 11 | | | | | | | | | | | |
| 12 | | | | | | | | | | | |
| 13 | | | | | | | | | | | |
| 14 | | | | | | | | | | | |
| 15 | | | | | | | | | | | |
| X | 1.952 | 105.8 | 2060 | | 2.064 | 2.048 | 1.144 | | | | |
| R | 0.08 | 4 | 100 | | 0.01 | 0.02 | 0.03 | | | | |
| CUSTOMER | | | | | | | | | | | |
| SAMPLE | | | | | | | | | | | |

TEST INSTRUMENT:

L: Agilent/HP4284A+Agilent/HP42841A

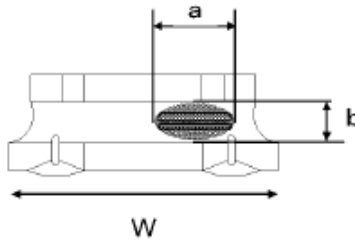
RDC: DIGITAL MILLIOHM METER Chroma 16502, or equivalent

Isat & Irms: Agilent/HP4284A+Agilent/HP42841A

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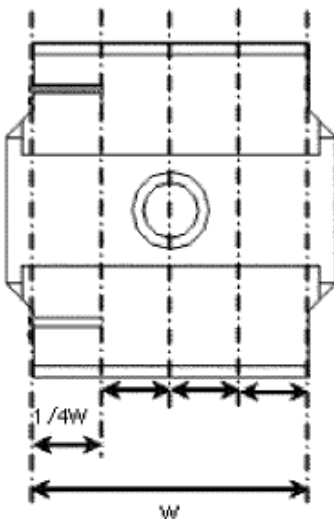
Exposed wire tolerance limit of coating resin part on product side
Size of exposed wire occurring to coating resin is specified below.





- ① Width direction (dimension a) : Acceptable when $a \leq W/2$
Nonconforming when $a > W/2$
- ② Length direction (dimension b) : Dimension b is not specified.
- ③ When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

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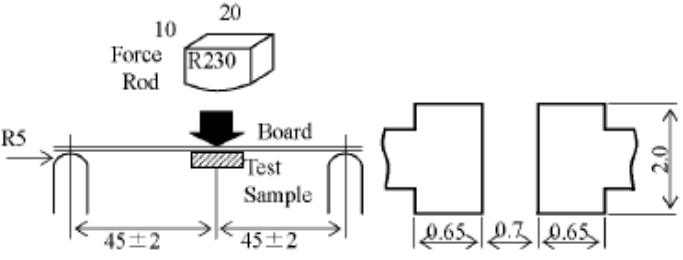
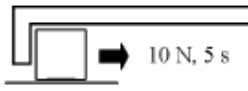
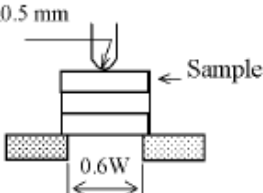
Electrode appearance criterion for exposed wire



| Cross section of joint part | Appearance judgment |
|---|--|
|  Only top side of wire is exposed. (regardless of whole top side of wire exposed) | Good |
|  Wire is soldered insufficiently and less than half of outer diameter is covered with solder. | Less than one-quarter of width of insufficiently soldered portion shall be acceptable. (More than one-quarter shall be segregated as reject.) |

LVM202012 Series Specification

13 MECHANICAL Characteristics

| | | |
|--------------------------------|-----------------------------|---|
| Resistance to deflection | No damage. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions show in Table 15 As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm.</p>  <p>Land dimensions</p> <p>Test board size : 100×40×1.0 Test board material: glass epoxy-resin Solder cream thickness: 0.1</p> <p>Unit: mm</p> |
| Adhesion of Terminal electrode | Shall not come off PC board | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15</p>  <p>Applied force: 10 N to X and Y directions. Duration: 5 s. Solder cream thickness: 0.1 mm (Refer to recommended Land Pattern Dimensions defined in "Precaution")</p> |
| Body strength | No damage. | <p>Applied force: 20 N Duration: 10 s</p>  |

LVM202012 Series Specification

14 ENVIRONMENT TESTS

| Test Item | Standard | Test method | | | | | | | | | | | | | | | |
|---------------------------------------|--|---|--------------------|-------------------|-----------------|--|-------------------|----------------------------------|------|---------------------------------------|-----------|---|------------------|------------|---|-----------|-----------|
| Resistance to vibration | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15. Then it shall be submitted to below test conditions.</p> <table><tr><td>Frequency range</td><td>10Hz ~55 Hz</td></tr><tr><td>Total Amplitude</td><td>1.5 mm (May not exceed acceleration 196 m/S²)</td></tr><tr><td>Sweeping Method</td><td>10Hz to 55Hz to 10 Hz for 1 min.</td></tr><tr><td>Time</td><td>For 2 hours on each X, Y, and Z axis.</td></tr></table> | Frequency range | 10Hz ~55 Hz | Total Amplitude | 1.5 mm (May not exceed acceleration 196 m/S ²) | Sweeping Method | 10Hz to 55Hz to 10 Hz for 1 min. | Time | For 2 hours on each X, Y, and Z axis. | | | | | | | |
| Frequency range | 10Hz ~55 Hz | | | | | | | | | | | | | | | | |
| Total Amplitude | 1.5 mm (May not exceed acceleration 196 m/S ²) | | | | | | | | | | | | | | | | |
| Sweeping Method | 10Hz to 55Hz to 10 Hz for 1 min. | | | | | | | | | | | | | | | | |
| Time | For 2 hours on each X, Y, and Z axis. | | | | | | | | | | | | | | | | |
| Resistance to soldering heat (Reflow) | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test sample shall be exposed to reflow oven at 230± 5 deg C for 40 seconds, with peak temperature at 260± 5 deg C for 5 seconds, 2 times.</p> <p>Test board thickness: 1.0 mm Test board material: glass epoxy-resin</p> | | | | | | | | | | | | | | | |
| Solderability | At least 90 % of surface of terminal electrode is covered by new solder. | <p>The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25 %.</p> <table><tr><td>Solder Temperature</td><td>245± 5 deg C</td></tr><tr><td>Time</td><td>5± 1.0 s.</td></tr><tr><td>Immersing Speed</td><td>25 mm/s</td></tr></table> | Solder Temperature | 245 ± 5 deg C | Time | 5 ± 1.0 s. | Immersing Speed | 25 mm/s | | | | | | | | | |
| Solder Temperature | 245 ± 5 deg C | | | | | | | | | | | | | | | | |
| Time | 5 ± 1.0 s. | | | | | | | | | | | | | | | | |
| Immersing Speed | 25 mm/s | | | | | | | | | | | | | | | | |
| Temperature characteristics | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>Measurement of inductance shall be taken at temperature range within -40 deg C to +125 deg C. With reference to inductance value at +20 deg C, change rate shall be calculated.</p> | | | | | | | | | | | | | | | |
| Thermal shock | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.</p> <p>Conditions of steps for 1 cycle</p> <table><tr><td>Step</td><td>Temperature</td><td>Time (min)</td></tr><tr><td>1</td><td>-40± 3 deg C</td><td>30± 3</td></tr><tr><td>2</td><td>Room Temp.</td><td>3 maximum</td></tr><tr><td>3</td><td>85± 2 deg C</td><td>30± 3</td></tr><tr><td>4</td><td>Room Temp</td><td>3 maximum</td></tr></table> | Step | Temperature | Time (min) | 1 | -40 ± 3 deg C | 30 ± 3 | 2 | Room Temp. | 3 maximum | 3 | 85 ± 2 deg C | 30 ± 3 | 4 | Room Temp | 3 maximum |
| Step | Temperature | Time (min) | | | | | | | | | | | | | | | |
| 1 | -40 ± 3 deg C | 30 ± 3 | | | | | | | | | | | | | | | |
| 2 | Room Temp. | 3 maximum | | | | | | | | | | | | | | | |
| 3 | 85 ± 2 deg C | 30 ± 3 | | | | | | | | | | | | | | | |
| 4 | Room Temp | 3 maximum | | | | | | | | | | | | | | | |
| Low temperature life test | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15. After that, the test samples shall be placed at test conditions as shown in below table.</p> <table><tr><td>Temperature</td><td>-40± 2 deg C</td></tr><tr><td>Time</td><td>500 +24/-0 h</td></tr></table> | Temperature | -40 ± 2 deg C | Time | 500 +24/-0 h | | | | | | | | | | | |
| Temperature | -40 ± 2 deg C | | | | | | | | | | | | | | | | |
| Time | 500 +24/-0 h | | | | | | | | | | | | | | | | |



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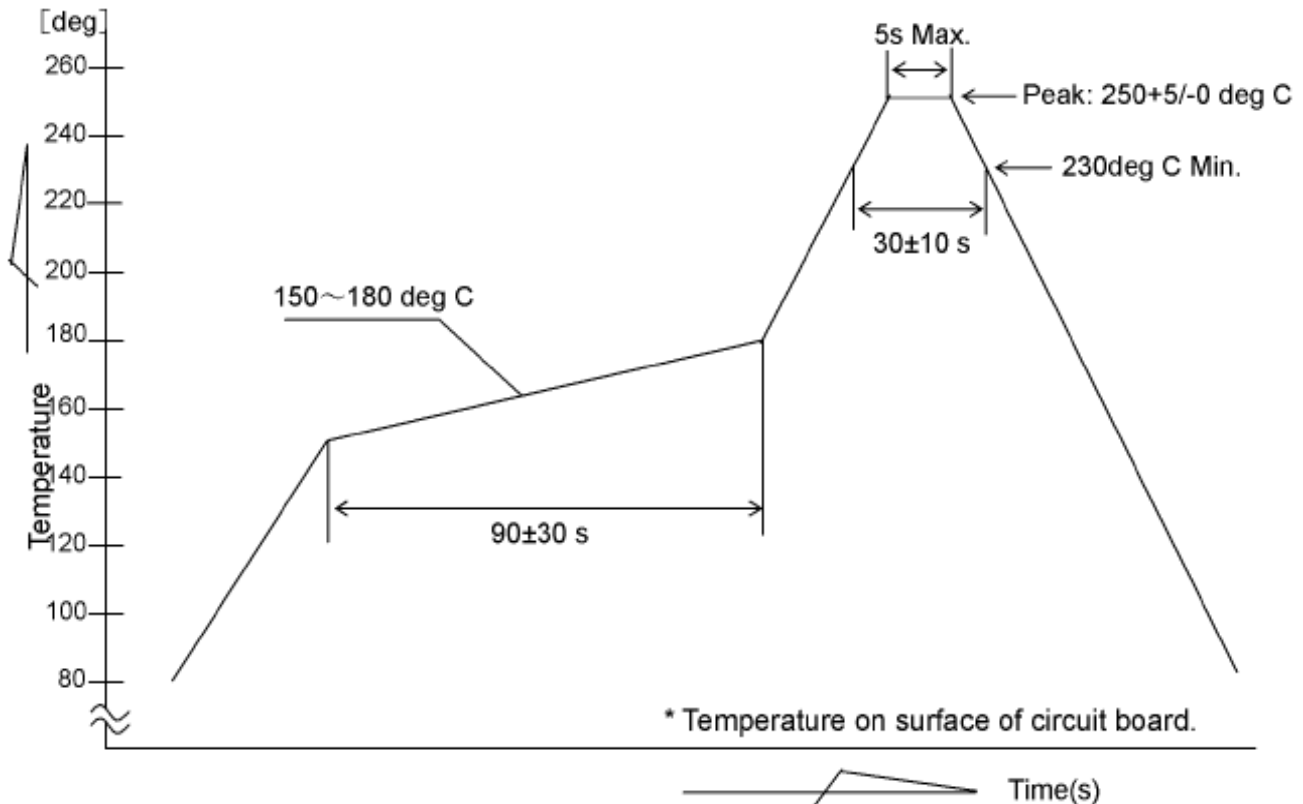
14 ENVIRONMENT TESTS

| Test Item | Standard | Test method | | | | | | | | |
|---------------------------------------|--|--|-------------|------------------|-----------------|-------------------------------------|-----------------|-------------------------------------|------|--------------|
| Loading at high temperature life test | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15</p> <p>The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table.</p> <table><tr><td>Temperature</td><td>85± 2 deg C</td></tr><tr><td>Applied current</td><td>Rated current (Refer to Table 1)</td></tr><tr><td>Time</td><td>500 +24/-0 h</td></tr></table> | Temperature | 85 ± 2 deg C | Applied current | Rated current (Refer to Table 1) | Time | 500 +24/-0 h | | |
| Temperature | 85 ± 2 deg C | | | | | | | | | |
| Applied current | Rated current (Refer to Table 1) | | | | | | | | | |
| Time | 500 +24/-0 h | | | | | | | | | |
| Damp heat life test | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15</p> <p>The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.</p> <table><tr><td>Temperature</td><td>60± 2 deg C</td></tr><tr><td>Humidity</td><td>90~95 %RH</td></tr><tr><td>Time</td><td>500 +24/-0 h</td></tr></table> | Temperature | 60 ± 2 deg C | Humidity | 90~95 %RH | Time | 500 +24/-0 h | | |
| Temperature | 60 ± 2 deg C | | | | | | | | | |
| Humidity | 90~95 %RH | | | | | | | | | |
| Time | 500 +24/-0 h | | | | | | | | | |
| Loading under damp heat life test | $\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance. | <p>The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 15</p> <p>The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.</p> <table><tr><td>Temperature</td><td>60± 2 deg C</td></tr><tr><td>Humidity</td><td>90~95 %RH</td></tr><tr><td>Applied current</td><td>Rated current (Refer to Table 1)</td></tr><tr><td>Time</td><td>500 +24/-0 h</td></tr></table> | Temperature | 60 ± 2 deg C | Humidity | 90~95 %RH | Applied current | Rated current (Refer to Table 1) | Time | 500 +24/-0 h |
| Temperature | 60 ± 2 deg C | | | | | | | | | |
| Humidity | 90~95 %RH | | | | | | | | | |
| Applied current | Rated current (Refer to Table 1) | | | | | | | | | |
| Time | 500 +24/-0 h | | | | | | | | | |

| | |
|------------------------------|--|
| Standard measuring condition | Unless otherwise specified, the test samples are placed at room temperature and humidity and measured within 48 hours after exposure to test conditions. |
|------------------------------|--|

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15 ENVIRONMENT TESTS

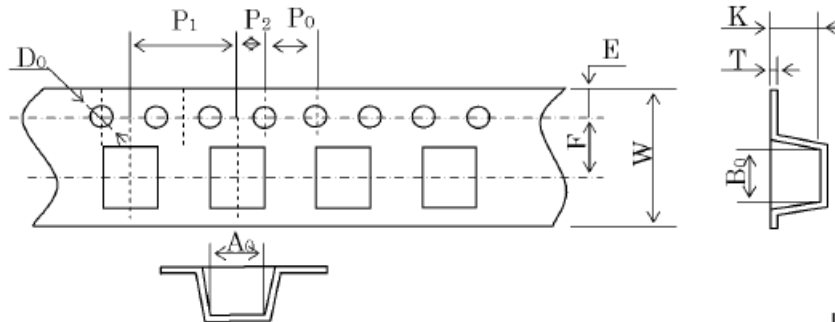


The products may be exposed to reflow soldering process of above profile up to two times.

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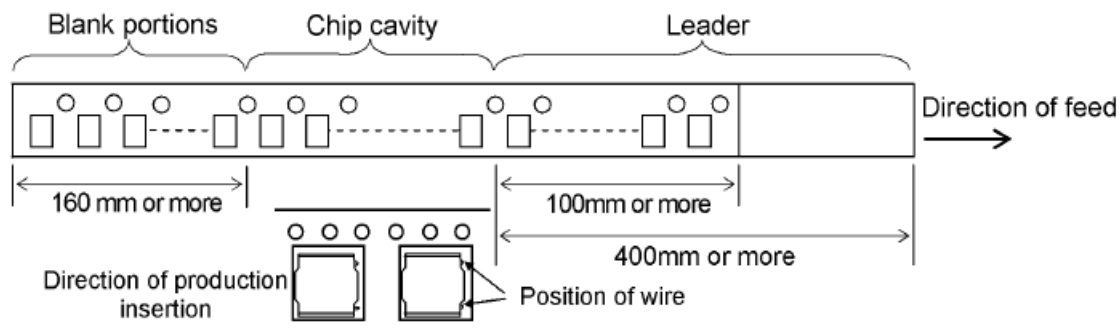
1. Dimensions



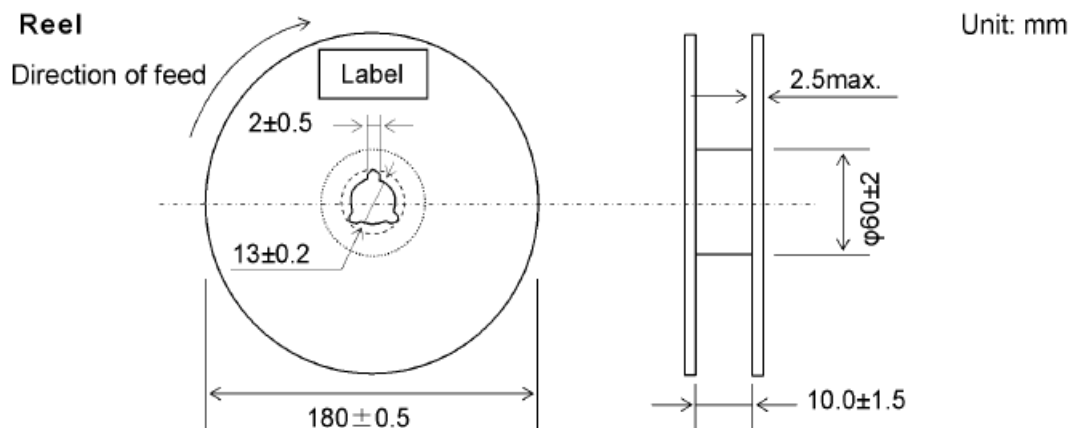
Unit: mm

| A ₀ | B ₀ | W | F | E | P ₁ | P ₂ | P ₀ | D ₀ | T | K |
|----------------|----------------|-------------|-------------|--------------|----------------|----------------|----------------|---------------------|---------------|--------------|
| 2.2 ±0.1 | 2.2 ±0.1 | 8.0 ±0.2 | 3.5 ±0.1 | 1.75 ±0.1 | 4.0 ±0.1 | 2.0 ±0.05 | 4.0 ±0.1 | φ 1.5 +0.1 -0 | 0.25 ±0.05 | 1.3 ±0.05 |

2. Direction of rolling

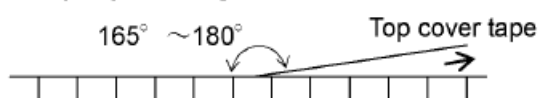


3. Reel



Label position: On the opposite side of sprocket holes side of reel

4. Top tape strength



Peel-off strength : 0.1 N~1.3 N
Peel-off angle : 165° ~180°
Peel-off speed : 300 mm/min



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17 PACKING FORM

1. The number of components

A tape & reel package contains 2500 inductors.

2. Tape and Reel

Emboss carrier tape: 8mm-width and 4 mm-pitch

Reel: 180 mm-diameter

3. The allowable number of empty chip cavities

Maximum two (2) chip cavities missing product may exist in a reel but they may not be consecutive two cavities.

4. Marking

The following items shall be marked legibly on per tape & reel package.

- (1) Customer part No.
- (2) Our part No.
- (3) Supplier name (TAIYO YUDEN CO., LTD.)
- (4) Control No.
- (5) Date (stamp)
- (6) Quantity
- (7) Country of the origin

5. Dimensions of packing box (for Tape & Reel package)

| | |
|--------|--------|
| Length | 135 mm |
| Width | 185 mm |
| Height | 185 mm |

Standard Quantity: 25000 pcs.

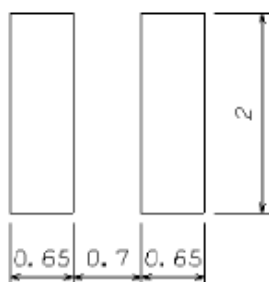
A packing box contains 10 reels maximum.

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16 Precautions

1. Surface Mounting

- Mounting and soldering conditions should be checked beforehand.
- Applicable soldering process to this products is reflow soldering only.
- Recommended Land-Pattern :



(Unit: mm)

2. Handling

- Keep the products away from all magnets and magnetic objects.
- Be careful not to subject the products to excessive mechanical shocks.
- Please avoid applying impact to the products after mounted on pc board.
- Avoid ultrasonic cleaning.
- Between the terminals on the bottom of the products, please do not provided pattern.
Parts are arranged around the products (top panel, side) on the surface of the products.
Please do not contact.

3. Storage

To prevent deterioration of the solderability of terminal electrodes and/or the packing materials of the products, please store the products under following storage conditions.

Ambient temperature range -5 deg C to 40 deg C

Humidity 70 % RH maximum

Even under the ideal storage conditions, solderability of inductor's electrode deteriorates as time passes, so inductors should be used within 6 months after the delivery time.

4. Regarding Regulations

- Any Class- I or Class- II ozone-depleting substance (ODS) listed in the Clean Air Act in US for regulation is not included in the products or applied to the products at any stage of whose manufacturing processes.
- Certain brominated flame retardants (PBBs, PBDEs) are not used at all.
- The products of this specifications are not subject to the Export Trade Control Order in Japan or the Export Administration Regulations in US.

5. RoHS compliance

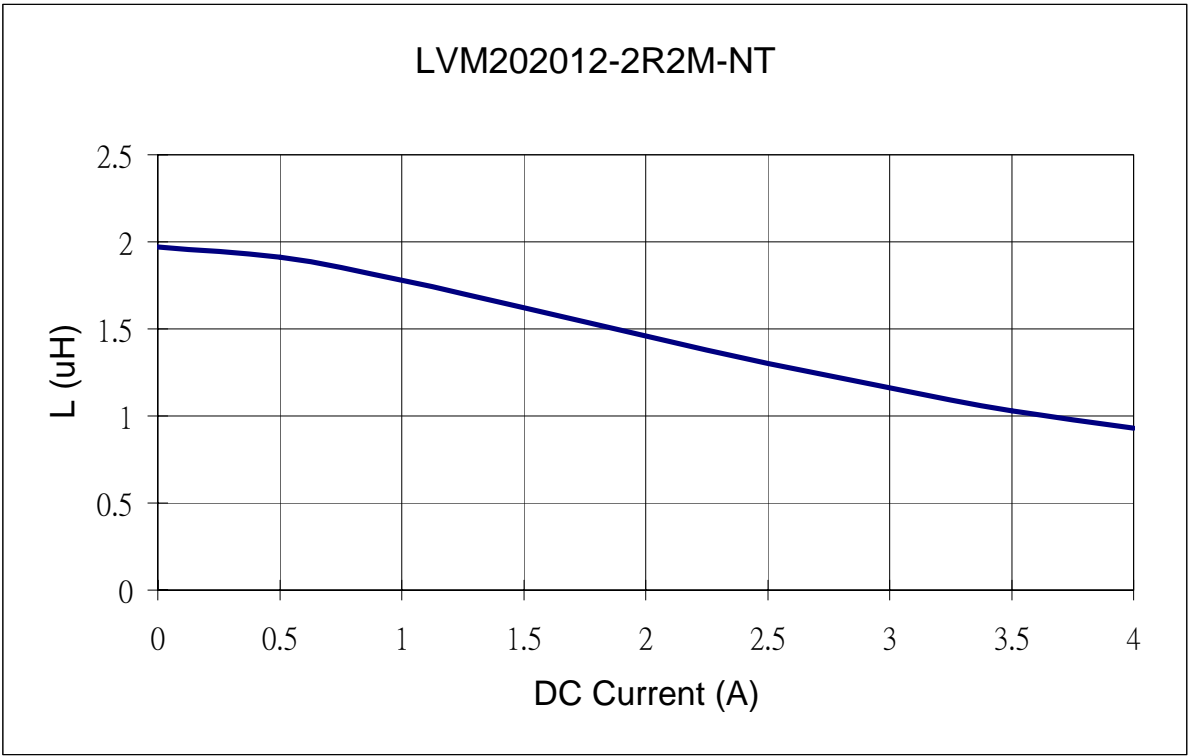
This product conforms to "RoHS compliance".



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14 Curve:

| IDC(A) | L(uH) |
|--------|-------|
| 0.0 | 1.97 |
| 0.5 | 1.91 |
| 1.0 | 1.78 |
| 1.5 | 1.62 |
| 2.0 | 1.46 |
| 2.5 | 1.30 |
| 3.0 | 1.16 |
| 3.5 | 1.03 |
| 4.0 | 0.93 |

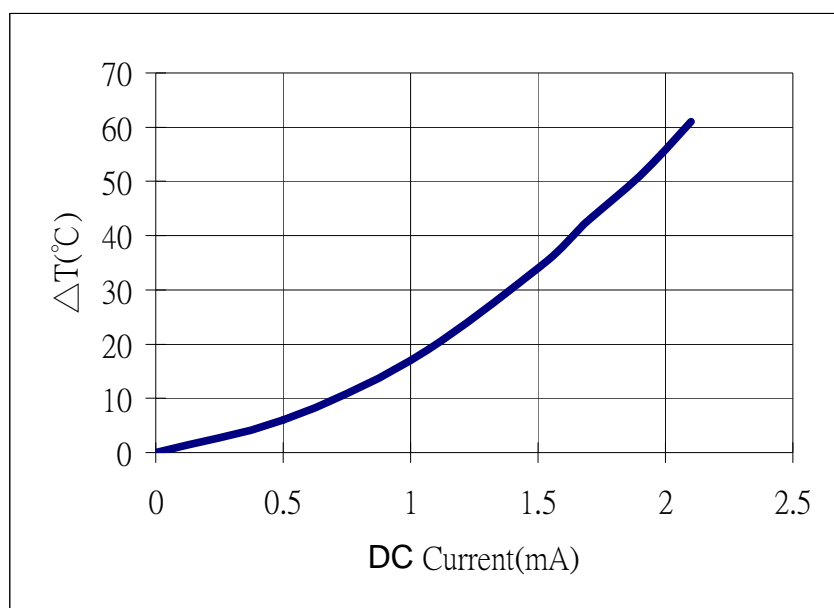




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18 Curve:

| IDC(A) | $\Delta T(^{\circ}\text{C})$ | surface temp($^{\circ}\text{C}$) | time(minute) |
|--------|------------------------------|------------------------------------|--------------|
| 0 | 0 | 25 | 30 |
| 0.5 | 6 | 31 | 30 |
| 1.0 | 17 | 42 | 30 |
| 1.5 | 34 | 59 | 30 |
| 1.7 | 43 | 68 | 30 |
| 1.9 | 51 | 76 | 30 |
| 2.1 | 61 | 86 | 30 |



Temperature test conditions:

1. Start as the atmosphere temp. @25 $^{\circ}\text{C}$.
2. Take the reading once it becomes stable.
3. Need to wait 90Sec at least, then change to the next applied current value.